

Memories

- · Memories in Verilog
- Memories on the FPGA
- External Memories
 - -- SRAM (async, sync)
 - -- DRAM
 - -- Flash

Memories: a practical primer

- The good news: huge selection of technologies
 - Small & faster vs. large & slower
 - Every year capacities go up and prices go down
 - New kid on the block: high density, fast flash memories
 - Non-volatile, read/write, no moving parts! (robust, efficient)
- The bad news: perennial system bottleneck
 - Latencies (access time) haven't kept pace with cycle times
 - Separate technology from logic, so must communicate between silicon, so physical limitations (# of pins, R's and C's and L's) limit bandwidths
 - New hopes: capacitive interconnect, 3D IC's
 - Likely the limiting factor in cost & performance of many digital systems: designers spend a lot of time figuring out how to keep memories running at peak bandwidth
 - "It's the memory, stupid"

Memories in Verilog

```
reg bit; // a single register

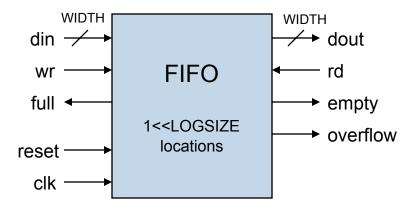
    reg [31:0] word; // a 32-bit register

reg [31:0] array[15:0]; // 16 32-bit regs
wire [31:0] read_data,write_data;
 wire [3:0] index;
 // combinational (asynch) read
 assign read_data = array[index];
 // clocked (synchronous) write
 always @(posedge clock)
     array[index] <= write_data;</pre>
```

Multi-port Memories (aka regfiles)

```
reg [31:0] regfile[30:0]; // 31 32-bit words
// Beta register file: 2 read ports, 1 write
wire [4:0] ra1,ra2,wa;
wire [31:0] rd1,rd2,wd;
assign ra1 = inst[20:16];
assign ra2 = ra2sel ? inst[25:21] : inst[15:11];
assign wa = wasel ? 5'd30 : inst[25:21];
// read ports
assign rd1 = (ra1 == 5'd31) ? 32'd0 : regfile[ra1];
assign rd2 = (ra2 == 5'd31) ? 32'd0 : regfile[ra2];
// write port
always @(posedge clk)
  if (werf) regfile[wa] <= wd;</pre>
assign z = \sim | rd1; // used in BEQ/BNE instructions
```

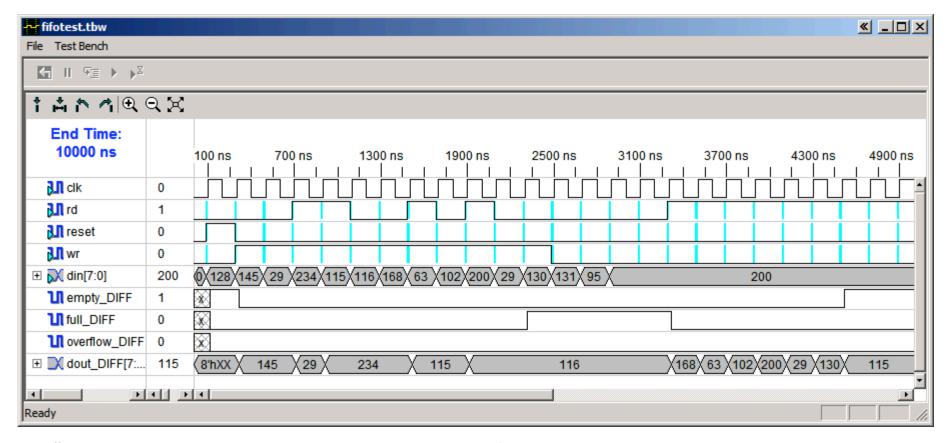
FIFOs



```
// a simple synchronous FIFO (first-in first-out) buffer
  Parameters:
      LOGSIZE
               (parameter) FIFO has 1<<LOGSIZE elements
      WIDTH
               (parameter) each element has WIDTH bits
// Ports:
      c1k
               (input) all actions triggered on rising edge
//
               (input) synchronously empties fifo
//
      reset
               (input, WIDTH bits) data to be stored
      din
//
//
               (input) when asserted, store new data
      wr
      full
               (output) asserted when FIFO is full
               (output, WIDTH bits) data read from FIFO
      dout
               (input) when asserted, removes first element
      rd
               (output) asserted when fifo is empty
      emptv
      overflow (output) asserted when WR but no room, cleared on next RD
module fifo #(parameter LOGSIZE = 2, // default size is 4 elements
                                       // default width is 4 bits
                        WIDTH = 4
            (input clk, reset, wr, rd, input [WIDTH-1:0] din.
             output full,empty,overflow, output [WIDTH-1:0] dout);
```

endmodule

FIFOs in action

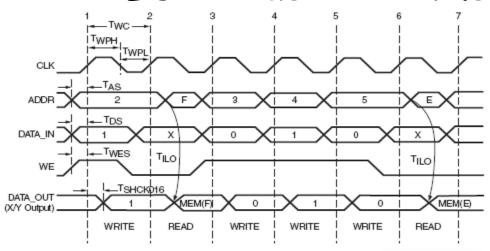


FPGA memory implementation

- Regular registers in logic blocks
 - Piggy use of resources, but convenient & fast if small
- [Xilinx Vertex II] use the LUTs:
 - Single port: 16x(1,2,4,8), 32x(1,2,4,8), 64x(1,2), 128x1
 - Dual port (1 R/W, 1R): 16x1, 32x1, 64x1
 - Can fake extra read ports by cloning memory: all clones are written with the same addr/data, but each clone can have a different read address
- [Xilinx Vertex II] use block ram:
 - 18K bits: 16Kx1, 8Kx2, 4Kx4with parity: 2Kx(8+1), 1Kx(16+2), 512x(32+4)
 - Single or dual port
 - Pipelined (clocked) operations
 - Labkit XCV2V6000: 144 BRAMs, 2952K bits total

MUXFX FXINA _ FXINB _ → ADDRESS RAM G3 🗀 G2 🗀 G1 □ ws DI BY 🗀 DATA_IN or Address SLICEWE[2:0] WSGEN WE CK MUXF5 - F5 ws DI ► ADDRESS RAM —>× G3 🗀 |G2| G1 □ BX 🗀 DATA_IN or Address CLK -SR 🗀 Slice Distributed RAM Diagram (Write Enable)

LUT-based RAMs

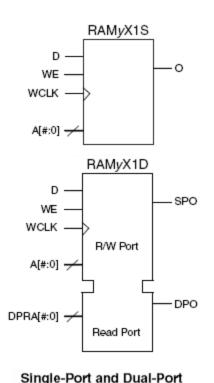


Slice Distributed RAM Timing Diagram

CLB Distributed RAM Switching Characteristics

		Speed Grade			
Description	Symbol	-6	-5	-4	Units
Sequential Delays					
Clock CLK to X/Y outputs (WE active) in 16 x 1 mode	T _{SHCKO16}	1.63	1.79	2.05	ns, Max
Clock CLK to X/Y outputs (WE active) in 32 x 1 mode	T _{SHCKO32}	1.97	2.17	2.49	ns, Max
Clock CLK to F5 output	T _{SHCKOF5}	1.77	1.94	2.23	ns, Max
Setup and Hold Times Before/After Clock CLK		•	•	•	
BX/BY data inputs (DIN)	T _{DS} /T _{DH}	0.53/0.09	0.58/0.10	0.67/0.11	ns, Min
F/G address inputs	T _{AS} /T _{AH}	0.40/ 0.00	0.44/ 0.00	0.50/ 0.00	ns, Min
SR input (WS)	T _{WES} /T _{WEH}	0.42/0.01	0.46/-0.01	0.53/0.01	ns, Min
Clock CLK				•	
Minimum Pulse Width, High	T _{WPH}	0.57	0.63	0.72	ns, Min
Minimum Pulse Width, Low	T _{WPL}	0.57	0.63	0.72	ns, Min
Minimum clock period to meet address write cycle time	Twc	1.14	1.25	1.44	ns, Min
Combinatorial Delays	•			•	
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.35	0.39	0.44	ns, Max

LUT-based RAM Modules



Distributed SelectRAM Primitive

Single-Port and Dual-Port Distributed SelectRAM

Primitive	RAM Size	Туре	Address Inputs
RAM16X1S	16 bits	single-port	A3, A2, A1, A0
RAM32X1S	32 bits	single-port	A4, A3, A2, A1, A0
RAM64X1S	64 bits	single-port	A5, A4, A3, A2, A1, A0
RAM128X1S	128 bits	single-port	A6, A5, A4, A3, A2, A1, A0
RAM16X1D	16 bits	dual-port	A3, A2, A1, A0
RAM32X1D	32 bits	dual-port	A4, A3, A2, A1, A0
RAM64X1D	64 bits	dual-port	A5, A4, A3, A2, A1, A0

Wider Library Primitives

Primitive	RAM Size	Data Inputs	Address Inputs	Data Outputs
RAM16x2S	16 x 2-bit	D1, D0	A3, A2, A1, A0	O1, O0
RAM32X2S	32 x 2-bit	D1, D0	A4, A3, A2, A1, A0	O1, O0
RAM64X2S	64 x 2-bit	D1, D0	A5, A4, A3, A2, A1, A0	O1, O0
RAM16X4S	16 x 4-bit	D3, D2, D1, D0	A3, A2, A1, A0	O3, O2, O1, O0
RAM32X4S	32 x 4-bit	D3, D2, D1, D0	A4,A3, A2, A1, A0	O3, O2, O1, O0
RAM16X8S	16 x 8-bit	D <7:0>	A3, A2, A1, A0	O <7:0>
RAM32X8S	32 x 8-bit	D <7:0>	A4,A3, A2, A1, A0	O <7:0>

// instantiate a LUT-based RAM module

RAM16X1S mymem #(.INIT(16'b011011110011010111100)) // msb first (.D(din),.O(dout),.WE(we),.WCLK(clock_27mhz), .A0(a[0]),.A1(a[1]),.A2(a[2]),.A3(a[3]));

Tools will often build these for you...

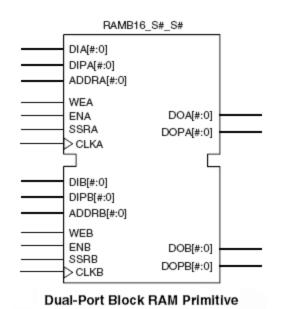
From Lab 2:

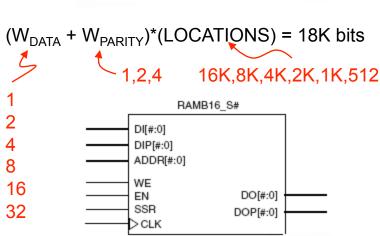
```
reg [7:0] segments:
always @ (switch[3:0]) begin
  case (switch[3:01)
  4'h0: segments[6:0] = 7'b0111111:
 4'h1: segments[6:0] = 7'b0000110:
  4'h2: segments[6:0] = 7'b1011011;
  4'h3: segments[6:0] = 7'b1001111;
  4'h4: segments[6:0] = 7'b1100110;
  4'h5: segments[6:0] = 7'b1101101;
  4'h6: segments[6:0] = 7'b1111101;
  4'h7: segments[6:0] = 7'b0000111;
  4'h8: segments[6:0] = 7'b11111111;
  4'h9: segments[6:0] = 7'b1100111;
  4'hA: segments[6:0] = 7'b1110111;
  4'hB: segments[6:0] = 7'b11111100;
  4'hC: segments[6:0] = 7'b1011000;
  4'hD: segments[6:0] = 7'b1011110;
  4'hE: segments[6:0] = 7'b1111001;
  4'hF: segments[6:0] = 7'b1110001;
  default: segments[6:0] = 7'b00000000;
  endcase
  segments[7] = 1'b0; // decimal point
end
```

```
_____
          HDL Synthesis
_____
Synthesizing Unit <lab2 2>.
   Related source file is "../lab2 2.v".
   Found 16x7-bit ROM for signal <$n0000>.
   Summary:
    inferred 1 ROM(s).
Unit < lab2 2> synthesized.
_____
Timing constraint: Default path analysis
Total number of paths / destination ports: 28 / 7
               7.244ns (Levels of Logic = 3)
Delay:
Source:
               switch<3> (PAD)
Destination: user1<0> (PAD)
Data Path: switch<3> to user1<0>
Cell:in->out fanout Delay Delay Logical Name
TBUF: T->O
            7 0.825 1.102 switch 3 IBUF
LUT4:I0->0
            1 0.439 0.517 Mrom n0000 inst lut4 01
                            user1 0 OBUF
               4.361
Total
                7.244ns (5.625ns logic, 1.619ns route)
                      (77.7% logic, 22.3% route)
```

Block Memories (BRAMs)

Dual-Port Block RAM Primitives





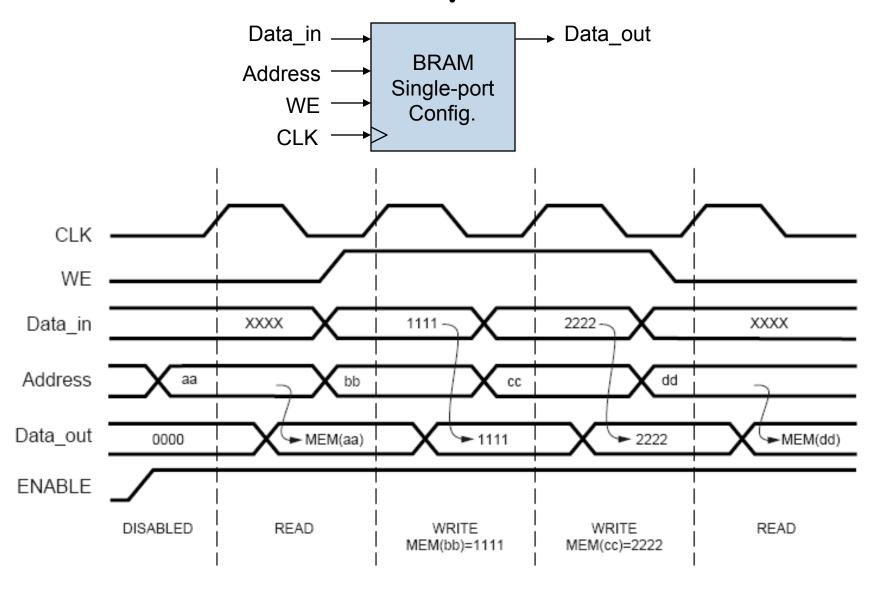
Single-Port Block RAM Primitive

Primitive	Port A Width	Port B Width
RAMB16_S1_S1		1
RAMB16_S1_S2		2
RAMB16_S1_S4	1	4
RAMB16_S1_S9	1	(8+1)
RAMB16_S1_S18		(16+2)
RAMB16_S1_S36		(32+4)
RAMB16_S2_S2		2
RAMB16_S2_S4		4
RAMB16_S2_S9	2	(8+1)
RAMB16_S2_S18		(16+2)
RAMB16_S2_S36		(32+4)
RAMB16_S4_S4		4
RAMB16_S4_S9	4	(8+1)
RAMB16_S4_S18	4	(16+2)
RAMB16_S4_S36		(32+4)
RAMB16_S9_S9		(8+1)
RAMB16_S9_S18	(8+1)	(16+2)
RAMB16_S9_S36		(32+4)
RAMB16_S18_S18	(16+2)	(16+2)
RAMB16_S18_S36	(10+2)	(32+4)
RAMB16_S36_S36	(32+4)	(32+4)

Single-Port Block RAM Primitives

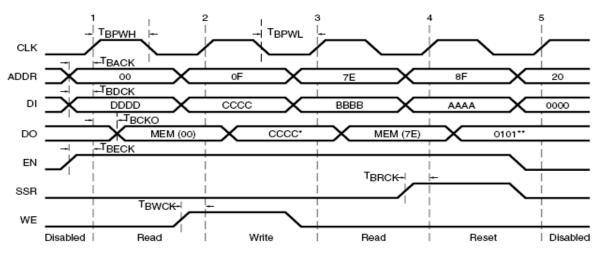
Primitive	Port Width
RAMB16_S1	1
RAMB16_S2	2
RAMB16_S4	4
RAMB16_S9	(8+1)
RAMB16_S18	(16+2)
RAMB16_S36	(32+4)

BRAM Operation



Source: Xilinx App Note 463

BRAM timing



^{*} Write Mode = 'WRITE_FIRST"

Block SelectRAM Timing Diagram

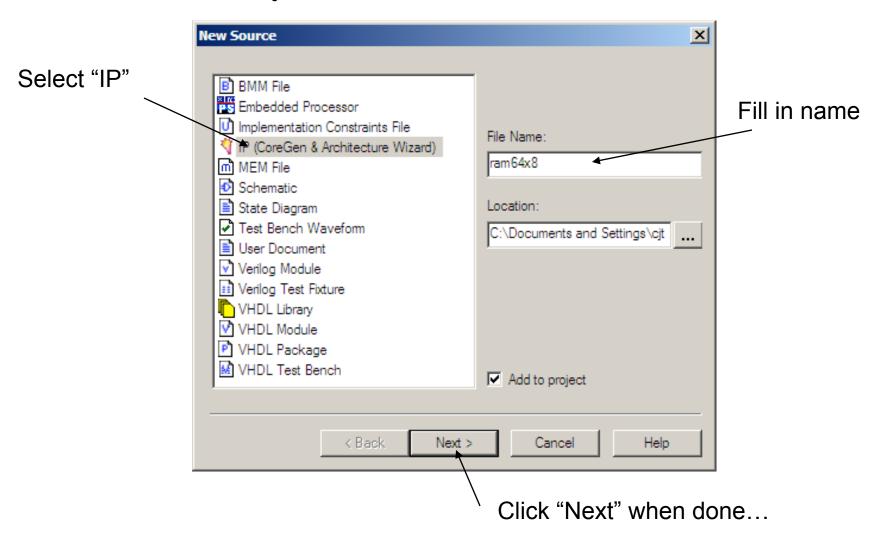
Block SelectRAM Switching Characteristics

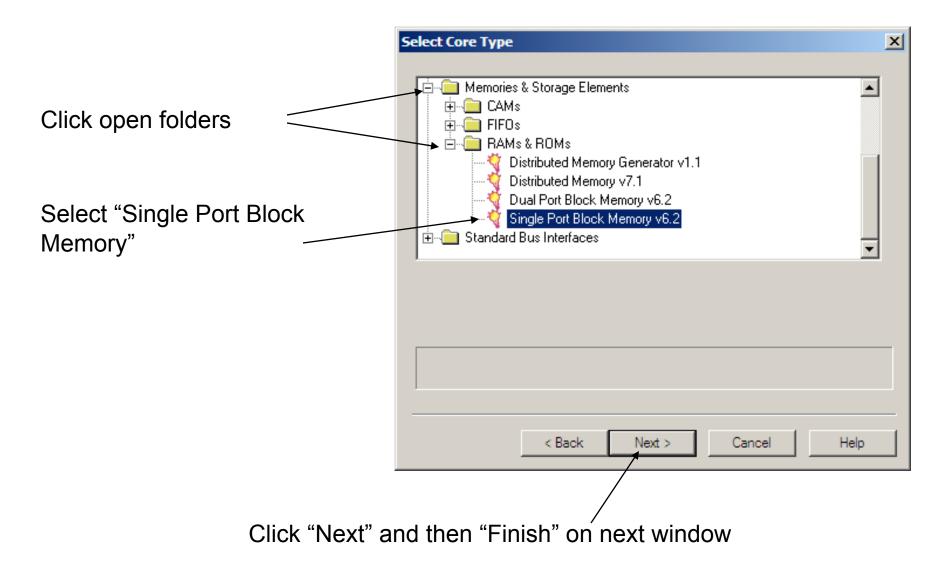
		Speed Grade			
Description	Symbol	-6	-5	-4	Units
Sequential Delays					
Clock CLK to DOUT output	T _{BCKO}	2.10	2.31	2.65	ns, Max
Setup and Hold Times Before Clock CLK					
ADDR inputs	T _{BACK} /T _{BCKA}	0.29/ 0.00	0.32/ 0.00	0.36/ 0.00	ns, Min
DIN inputs	T _{BDCK} /T _{BCKD}	0.29/ 0.00	0.32/ 0.00	0.36/ 0.00	ns, Min
EN input	T _{BECK} /T _{BCKE}	0.95/-0.46	1.04/-0.50	1.20/-0.58	ns, Min
RST input	T _{BRCK} /T _{BCKR}	1.31/-0.71	1.44/-0.78	1.65/0.90	ns, Min
WEN input	T _{BWCK} /T _{BCKW}	0.57/0.19	0.63/-0.21	0.72/0.25	ns, Min
Clock CLK					
CLKA to CLKB setup time for different ports	T _{BCCS}	1.0	1.0	1.0	ns, min
Minimum Pulse Width, High	T _{BPWH}	1.17	1.29	1.48	ns, Min
Minimum Pulse Width, Low	T _{BPWL}	7 1.17	1.29	1.48	ns, Min

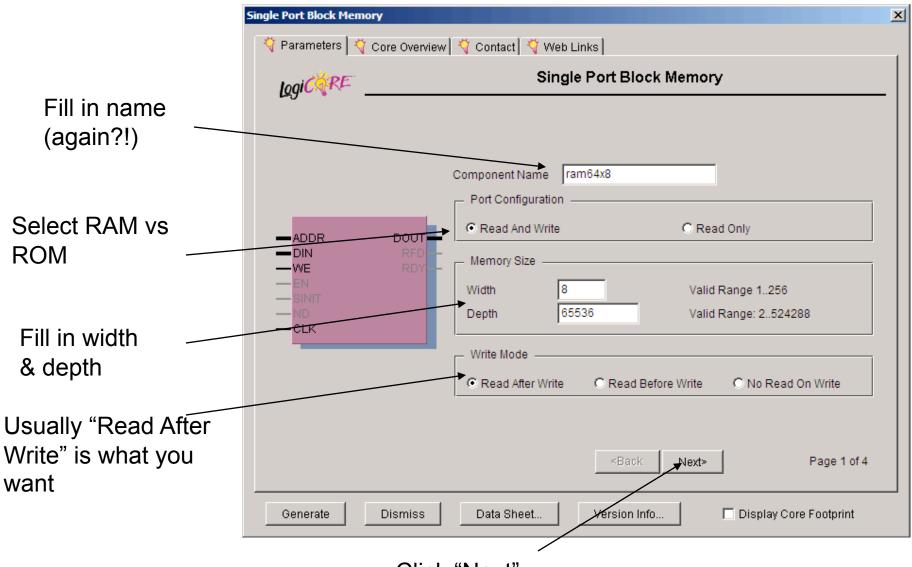
^{**} SRVAL = 0101

Using BRAMs (eg, a 64Kx8 ram)

• From menus: Project → New Source...







Click "Next" ...

🔻 Parameters 🐧 🐧 Core Overview 🐧 Contact 🧗 Web Links

Single Port Block Memory

Generate

Single Port Block Memory Logic RE Primitive Selection 16kx1 ▼ Optimize For Area C Select Primitive Design Options DOUT -ADDR -DIN Enable Pin Handshaking Pins Optional Pins: Register Inputs Register Options: Output Register Options Additional Output Pipe Stages 0 ▼ -CLK SINIT pin (sync. reset of output registers) Init Value (Hex) 0 ≺Back Next> Page 2 of 4

Version Info...

Display Core Footprint

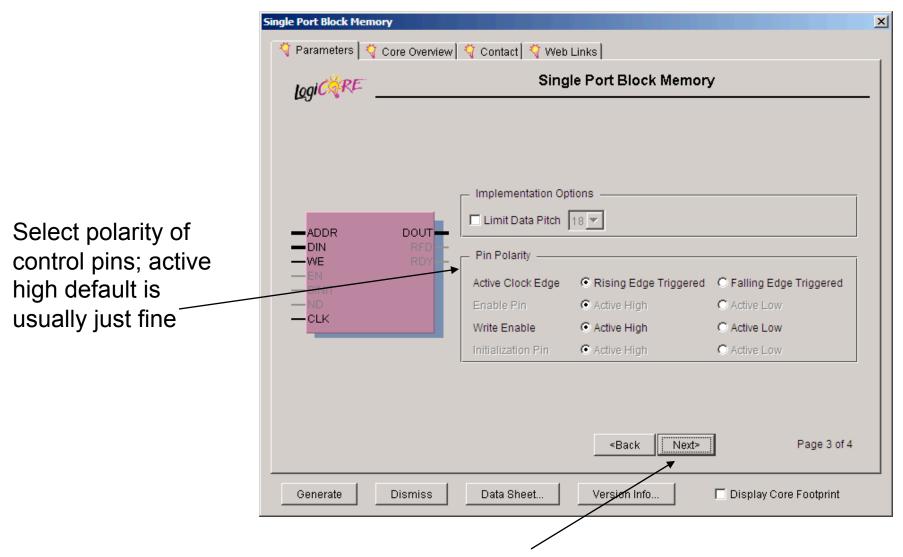
×

Can add extra control pins, but usually not

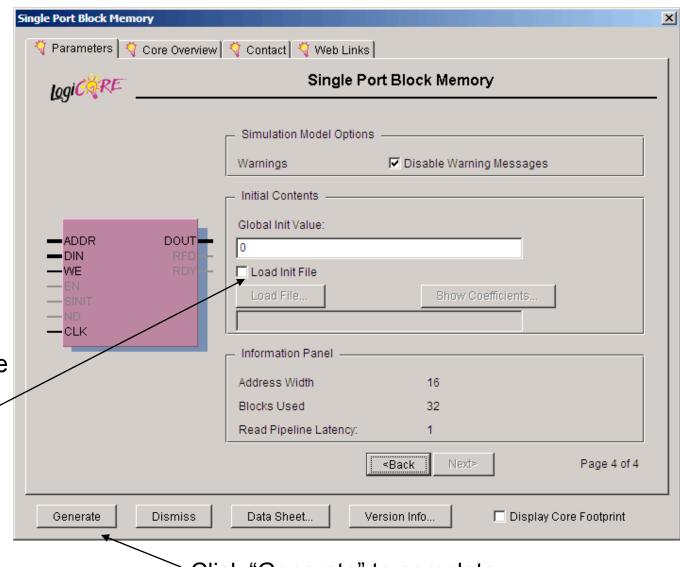
Click "Next" ...

Data Sheet...

Dismiss



Click "Next" ...



Click to name a .coe file that specifies initial contents (eg, for a ROM)

.coe file format

```
memory_initialization_radix=2;
memory_initialization_vector=
```

```
00000000,
00111110,
01100011,
00000011,
00000011,
00011110,
0000011,
0000011,
01100011,
00111110,
00000000,
00000000
```

Memory contents with location 0 first, then location 1, etc. You can specify input radix, in this example we're using binary. MSB is on the left, LSB on the right. Unspecified locations (if memory has more locations than given in .coe file) are set to 0.

Using result in your Verilog

Look at generated Verilog for module def'n:

```
module ram64x8 (addr,clk,din,dout,we);
  input [15 : 0] addr;
  input clk;
  input [7 : 0] din;
  output [7 : 0] dout;
  input we;
  ...
endmodule
```

• Use to instantiate instances in your code:

Memory Classification & Metrics

	Write nory	Non-Volatile	Read-Only Memory	
Random Access	Sequential Access	Read-Write Memory		
SRAM DRAM	FIFO	EPROM E ² PROM FLASH	Mask- Programmed ROM	

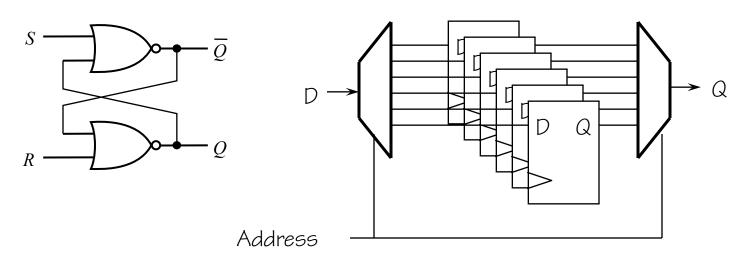
Key Design Metrics:

- 1. Memory Density (number of bits/mm²) and Size
- 2. Access Time (time to read or write) and Throughput
- 3. Power Dissipation

Static RAMs: Latch Based Memory

Set Reset Flip Flop

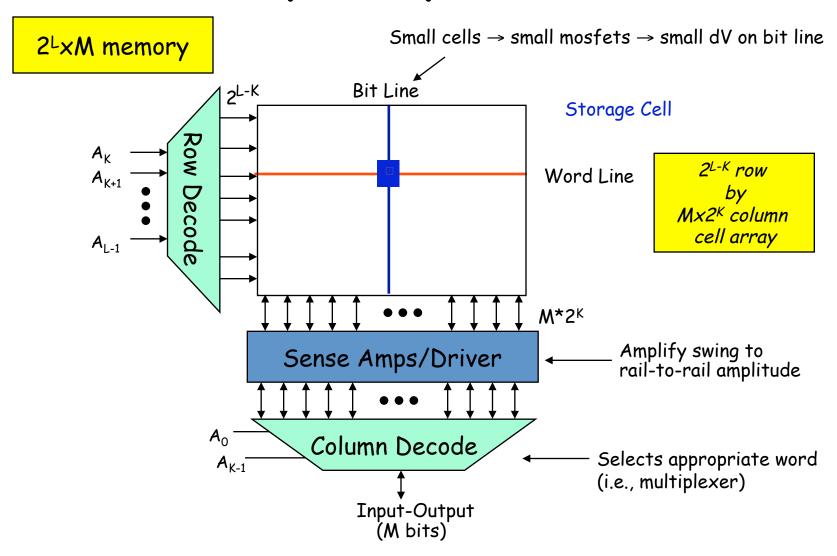
Register Memory



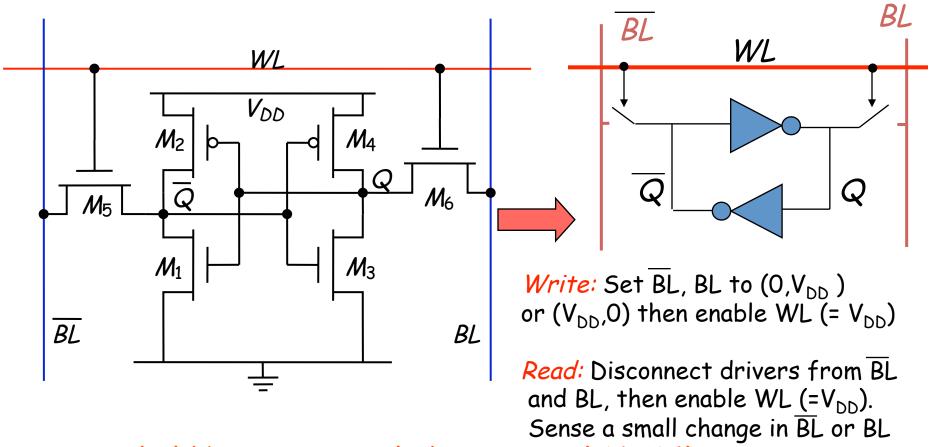
- Works fine for small memory blocks (e.g., small register files)
- Inefficient in area for large memories
- Density is the key metric in large memory circuits

How do we minimize cell size?

Memory Array Architecture

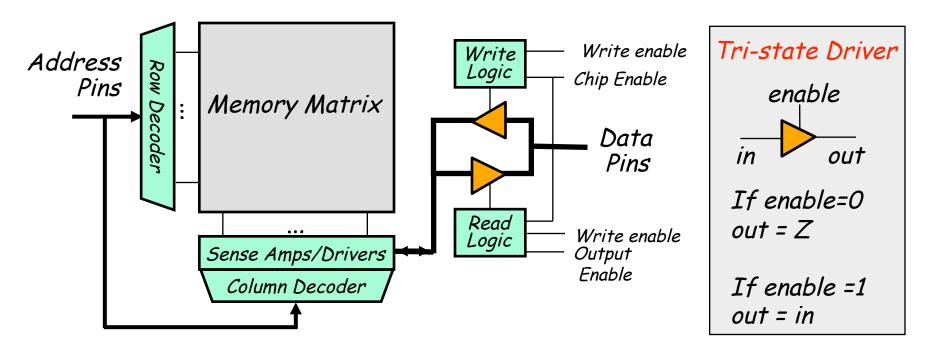


Static RAM (SRAM) Cell (The 6-T Cell)



- State held by cross-coupled inverters (M1-M4)
- Retains state as long as power supply turned on
- Feedback must be overdriven to write into the memory

Using External Memory Devices



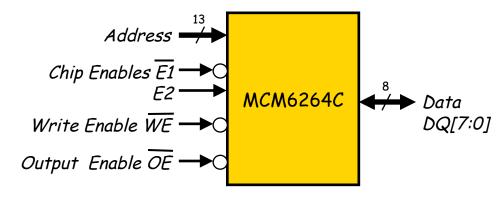
- Address pins drive row and column decoders
- Data pins are bidirectional: shared by reads and writes

Concept of "Data Bus"

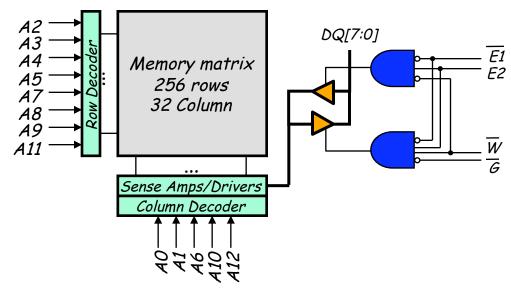
- Output Enable gates the chip's tristate driver
- Write Enable sets the memory's read/write mode
- Chip Enable/Chip Select acts as a "master switch"

MCM6264C 8K x 8 Static RAM

On the outside:



On the inside:



Same (bidirectional) data bus used for reading and writing

Chip Enables (E1 and E2)

E1 must be low and E2 must be high to enable the chip

Write Enable (WE)

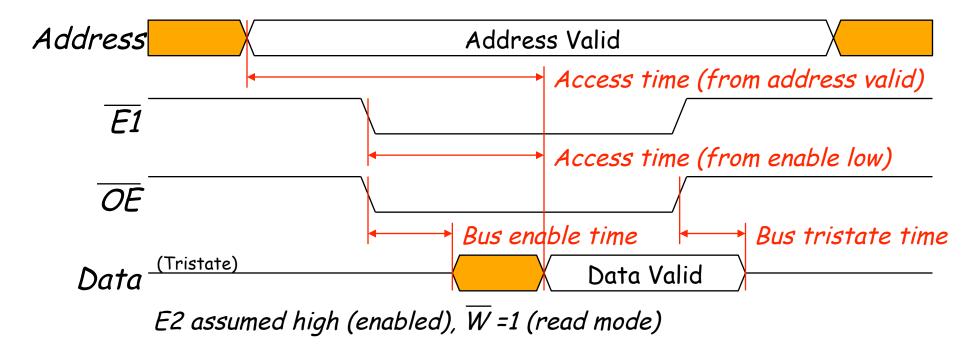
When low (and chip enabled), values on data bus are written to location selected by address bus

Output Enable $(\overline{OE} \text{ or } \overline{G})$

When low (and chip is enabled), data bus is driven with value of selected memory location

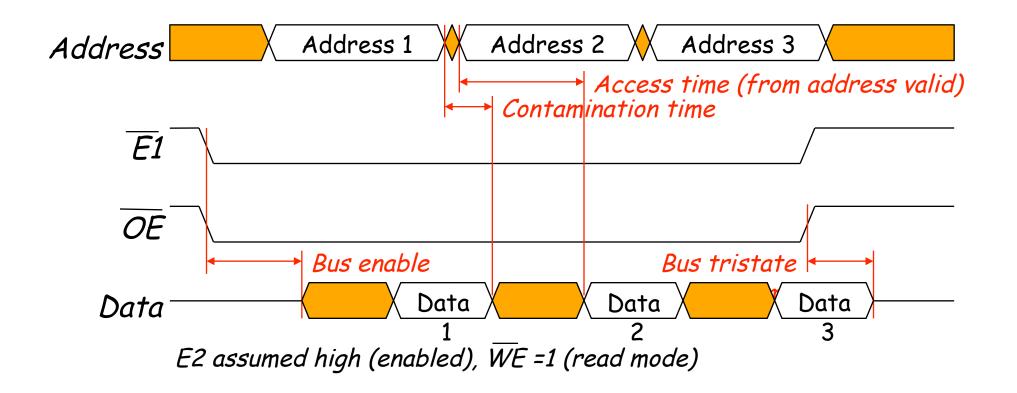


Reading an Asynchronous SRAM



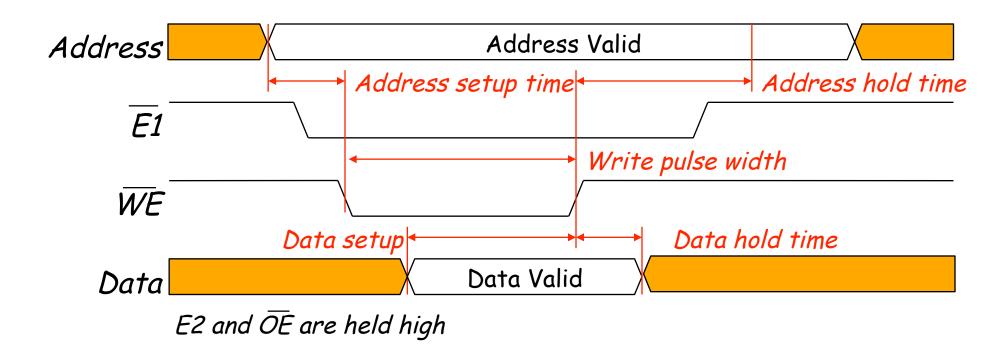
- Read cycle begins when all enable signals ($\overline{E1}$, $\overline{E2}$, \overline{OE}) are active
- Data is valid after read access time
 - Access time is indicated by full part number: $MCM6264CP-12 \rightarrow 12ns$
- Data bus is tristated shortly after \overline{OE} or E1 goes high

Address Controlled Reads



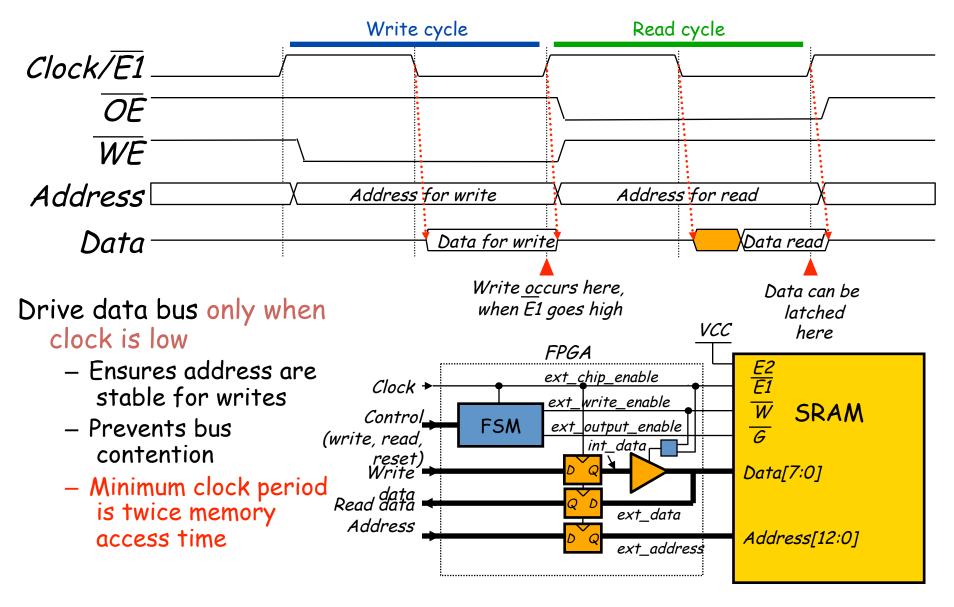
- · Can perform multiple reads without disabling chip
- Data bus follows address bus, after some delay

Writing to Asynchronous SRAM

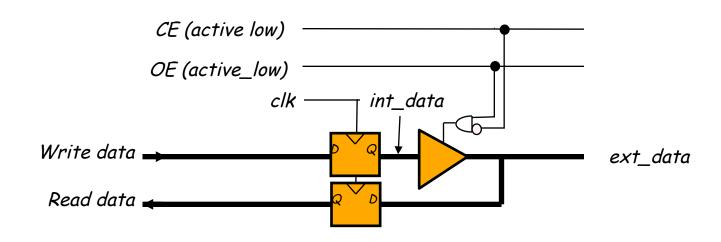


- Data latched when \overline{WE} or $\overline{E1}$ goes high (or E2 goes low)
 - Data must be stable at this time
 - Address must be stable before WE goes low
- Write waveforms are more important than read waveforms
 - Glitches to address can cause writes to random addresses!

Sample Memory Interface Logic



Tristate Data Buses in Verilog

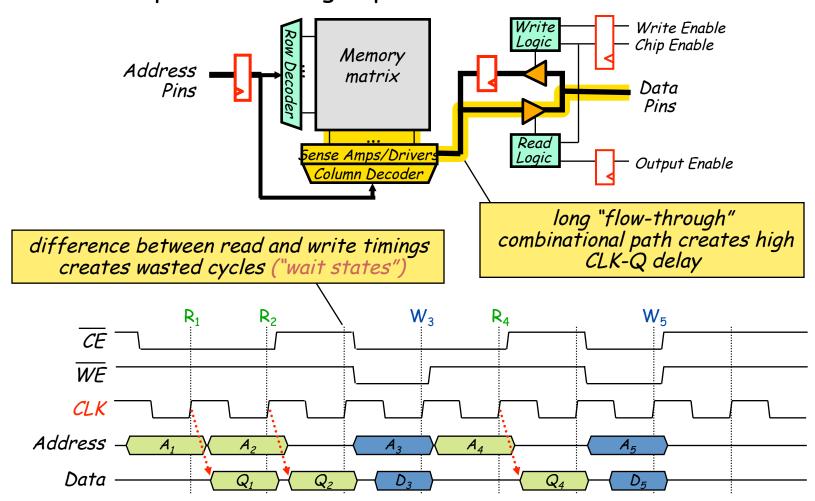


```
output CE,OE; // these signals are active low
inout [7:0] ext_data;
reg [7:0] read_data,int_data
wire [7:0] write_data;
always @(posedge clk) begin
  int_data <= write_data;
  read_data <= ext_data;
end

// Use a tristate driver to set ext_data to a value
assign ext_data = (~CE & OE) ? int_data : 8'hZZ;</pre>
```

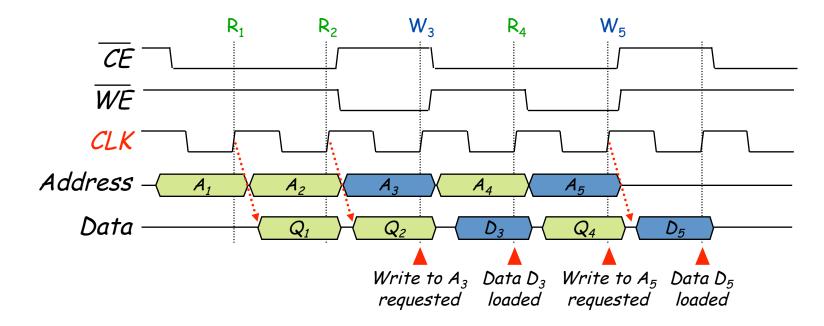
Synchronous SRAM Memories

 Clocking provides input synchronization and encourages more reliable operation at high speeds



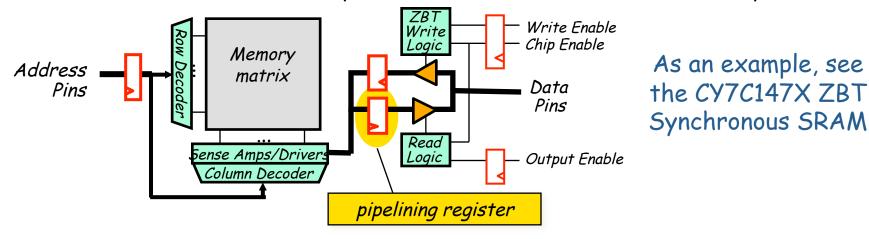
ZBT Eliminates the Wait State

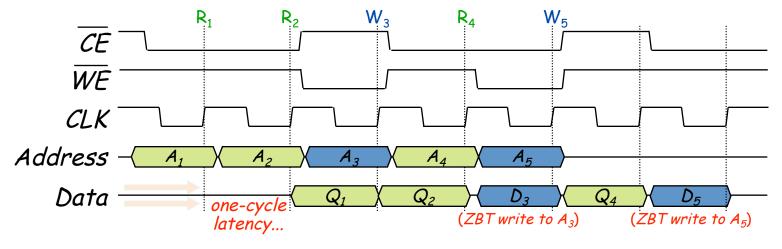
- The wait state occurs because:
 - On a read, data is available after the clock edge
 - On a write, data is set up before the clock edge
- ZBT ("zero bus turnaround") memories change the rules for writes
 - On a write, data is set up after the clock edge (so that it is read on the following edge)
 - Result: no wait states, higher memory throughput



Pipelining Allows Faster CLK

- Pipeline the memory by registering its output
 - Good: Greatly reduces CLK-Q delay, allows higher clock (more throughput)
 - Bad: Introduces an extra cycle before data is available (more latency)

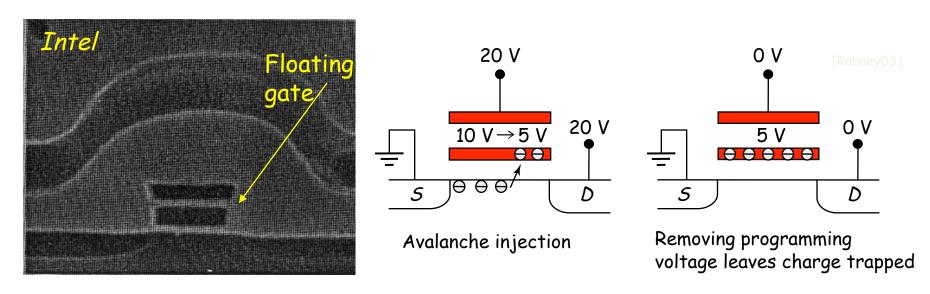




EEPROM

Electrically Erasable Programmable Read-Only Memory

EEPROM - The Floating Gate Transistor



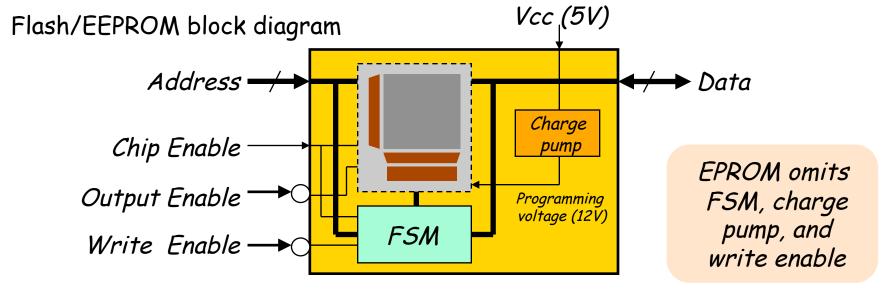
This is a non-volatile memory (retains state when supply turned off)

Usage: Just like SRAM, but writes are much slower than reads (write sequence is controlled by an FSM internal to chip)

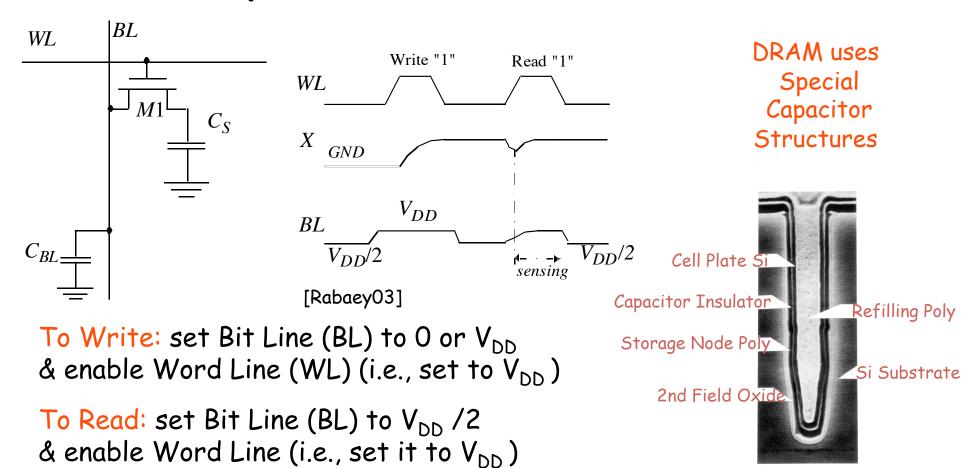
Common application: configuration data (serial EEPROM)

Interacting with Flash and (E)EPROM

- Reading from flash or (E)EPROM is the same as reading from SRAM
- Vpp: input for programming voltage (12V)
 - EPROM: Vpp is supplied by programming machine
 - Modern flash/EEPROM devices generate 12V using an on-chip charge pump
- EPROM lacks a write enable
 - Not in-system programmable (must use a special programming machine)
- For flash and EEPROM, write sequence is controlled by an internal FSM
 - Writes to device are used to send signals to the FSM
 - Although the same signals are used, one can't write to flash/EEPROM in the same manner as SRAM

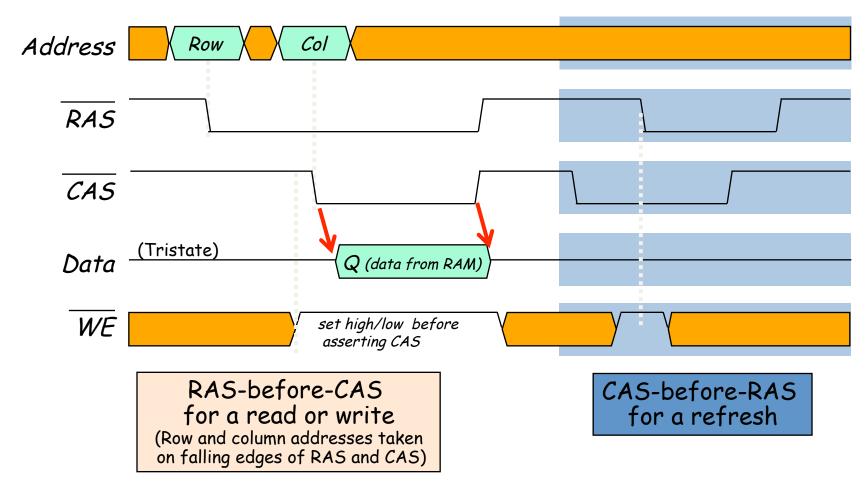


Dynamic RAM (DRAM) Cell



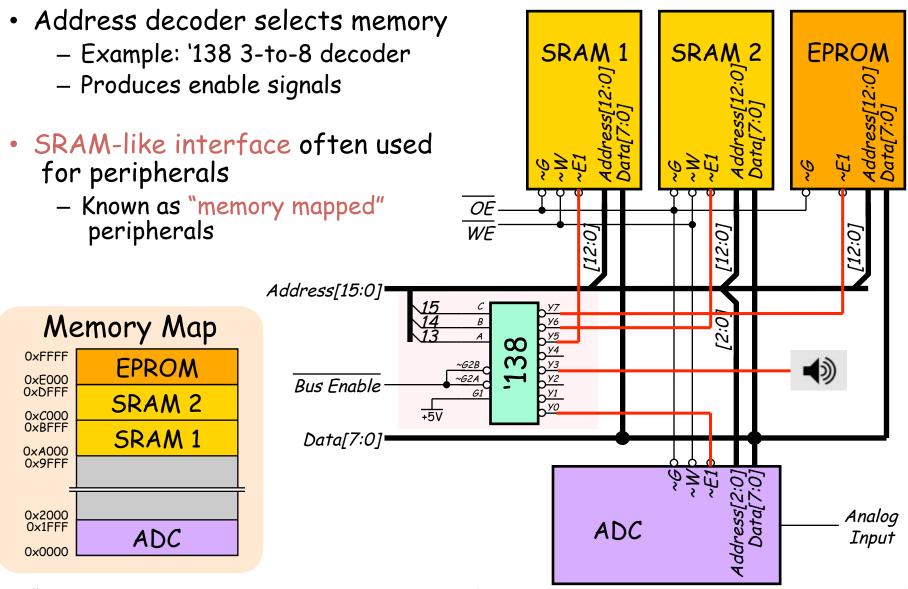
- DRAM relies on charge stored in a capacitor to hold state
- Found in all high density memories (one bit/transistor)
- Must be "refreshed" or state will be lost high overhead

Asynchronous DRAM Operation



 Clever manipulation of RAS and CAS after reads/writes provide more efficient modes: early-write, read-write, hidden-refresh, etc. (See datasheets for details)

Addressing with Memory Maps



Memory Devices: Helpful Knowledge

SRAM vs. DRAM

- SRAM holds state as long as power supply is turned on. DRAM must be "refreshed" - results in more complicated control
- DRAM has much higher density, but requires special capacitor technology.
- FPGA usually implemented in a standard digital process technology and uses SRAM technology

Non-Volatile Memory

- Fast Read, but very slow write (EPROM must be removed from the system for programming!)
- Holds state even if the power supply is turned off

Memory Internals

 Has quite a bit of analog circuits internally -- pay particular attention to noise and PCB board integration

Device details

- Don't worry about them, wait until 6.012 or 6.374

You Should Understand Why...

- control signals such as Write Enable should be registered
- a multi-cycle read/write is safer from a timing perspective than the single cycle read/write approach
- it is a bad idea to enable two tri-states driving the bus at the same time
- an SRAM does not need to be "refreshed" while a DRAM requires refresh
- an EPROM/EEPROM/FLASH cell can hold its state even if the power supply is turned off
- · a synchronous memory can result in higher throughput